

WAFER POLISHING SYSTEM

ABSTRACT

5 A wafer polishing system, at least comprising one polishing unit (1), wherein the polishing unit (1) comprises a wafer transmission channel (2) and at least two polishing modules (3); and the polishing modules (3) are located on both sides of the wafer transmission channel (2). After a polishing arm of one polishing module (3) obtains a wafer from a working position in the wafer transmission channel (2), the polishing process is completed; the wafer is then placed back to the
10 wafer transmission channel (2) along a first track (51); a wafer transfer device moves to transfer the wafer to another working position, and after a polishing arm of the other polishing module obtains the wafer from the working position along a second track (53), another polishing process is completed; and the first track (51), a moving track (52) of the wafer transfer device, and the form of the second track (53) are approximately Z-shaped. The wafer polishing system has a better
15 stability, a high flexibility and a better polishing effect.

Fig. 3